

Notice of References CitedApplication/Control No.
09/510,828Applicant(s)/Patent Under
Reexamination
HEMBREE ET AL.9Examiner
James MitchellArt Unit
2827

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NON-PATENT DOCUMENTS

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	U	IBM Technical Disclosure, "Cooling and Minimizing Temperature Gradient in Stacked Modules", Vol 19, Issue 2, Page 414, July 1, 1976
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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.